

Application No.: 10/046,812

Docket No.: 4481-044

Amendments to the Specification

At page 6 – please amend the first full paragraph with the following paragraph –

FIG. 5 illustrates a plan view of an integrated circuit (IC) 80 incorporating a track 42a-44b insulated according to a preferred embodiment of the present invention. Bond pads 92 are typically spaced along a periphery of the IC 80. To exemplify the requirements for an deployment of the present invention, it is useful to consider the circuit scenario where a bond pad 93 in the top left-hand corner of the IC 80 is connected to first circuit 72 via insulated track 44b. The track 44b is insulated by a shield 76 (as illustrated in FIG. 2 or FIG. 3) as the track 44b ~~and~~ traverses a second circuit 74. The second circuit 74 receives drive current from a current supply 88 which, in turn, is coupled to the first circuit 72. A laser diode 90 is coupled between the first circuit 72 and the second circuit 74 using bond pads to provide an off-chip connection. Clearly, the IC 80 also includes further tracks that connect bond pads to the components mounted on the IC 80.